



Product Change Notification

Change Notification #: 115878 - 00
Change Title: Intel® Server Chassis P4304XXMFEN2, Intel® Server Chassis P4308XXMFEN, PCN 115878-00, Label, Add BIS Regulatory Mark on the PSU Label
Date of Publication: November 1, 2017

Key Characteristics of the Change:
 Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	November 16, 2017
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Description of Change to the Customer:

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Intel is implementing the following changes on the Intel® Server Chassis listed in the Products Affected table (see below).

1. Add India BIS regulatory mark on the PSU label.



2. FUP550SNRPS part number rolling up from E96494-007 to E96494-008

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
P4304XXMFEN2	936416	H24211-006	H24211-007
P4308XXMFEN	916337	G51275-003	G51275-004

PCN Revision History:

Date of Revision:

November 1, 2017

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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